

Industrial 3D TLC NAND M.2 2280 NVMe SSD

MEC3F0 SERIES

PCIe Gen3x4 NVMe

3K PE Cycles 3D TLC NAND



PRODUCT FEATURES

- High-Quality 3D TLC NAND Flash Technology
- Industrial Standard PCIe Gen3.0x4 with NVMe 1.3 Compliant
- Global Wear Leveling and Early weak block retirement
- TRIM, NCQ, DEVSLP, Support PCIe Gen1.0/2.0/3.0 interface
- Lifetime Enhancements

Direct-to-TLC and SLC Cache enhancement to ensure the optimized WAF

Block/Page RAID function to ensure data recovery

StaticDataRefresh to keep data integrity

- Reliable Industrial grade integrated Active PMU and complete protection design with OVP, OCP, surge rejection and Short protection
- External DRAM to achieve the optimal sustained read/write performance.
- Power shielding firmware architecture to ensure power failure resilience
- AES256 Encryption and TCG Opal 2.0 compliant (Optional)
- SP SMART Toolbox
- SP SMART Embedded and SMART IoT service (by request)
- Driven by a growing number of IOPS in heavy data applications, the biggest benefit of PCIe-based SSD is increased performance.

 Reach up to R:3400 MB/s and W:3100 MB/s based on 32CE NAND flash.

PRODUCT SUMMARY

Capacities: 1TB, 2TB, 4TB, 8TB

Form Factor: M.2 2280 PCIe Solid State Drive (80 mm x 22 mm x 3.5 mm)

Compliance: PCle Gen3.0x4 compliant with Gen1.0/2.0/3.0

Command Sets: NVMe1.3 standard command protocol.

Performance :

	1TB	2TB	4TB	8TB
Sequential Read (MB/s Max.)	3,400	3,400	3,400	3,400
Sequential Write (MB/s Max.)	1,900	3,100	3,000	3,000
Random 4K Read (IOPS Max.)	330,000	670,000	570,000	570,000
Random 4K Write (IOPS Max.)	500,000	645,000	650,000	660,000

^{*} Actual performance may vary based on the specific model and capacity

Operating Temperature Range:

Normal: 0°C to 70°C

Extended: -15°C to 85°C (by request) Wide: -40°C to 85°C (by request)

Storage Temperature Range: -55°C to 95°C

Operating Voltage: 3.3 V ± 10%

· Power Consumption:

(Unit: mA)	1TB	2TB	4TB	8TB	
Read (Max.)	2000	1970	2425	1700	
Write (Max.)	1760	1820	2070	1970	
Stand-by (Avg.)	550	580	670	700	

^{*} Actual value may vary based on the specific model and capacity

- Data Retention @40 °C: 10 Years @ Life Begin; 1 Year @ Life End
- Endurance in Tera Bytes Written (TBW): (Unit: TB)

Workload	1TB	2TB	4TB	8TB	
Sequential	1340	2720	6070	TBD	
Enterprise	TBD	TBD	TBD	TBD	

TBW is estimated by formula TBW = (Capacity x PE Cycles) x (1+OP) x (WLE) / (WAF)

OP (Over Provision) = (Physical Capacity / Logical Capacity)-1

WAF = Write Amplification Factor

WLE = Wear Leveling Efficiency could be different depended on the workload or usage containing data size and access rate.

Sequential workload: Sequential write workload which is generated by VDBENCH script and tested by VDBENCH

Enterprise workload: Follow JESD219A enterprise workload which is generated by VDBENCH script and tested by VDBENCH.

Mechanical (IEC-60068):

Vibration: 15G, 10 ~ 2001Hz

Drop: 76cm

Shock: 1,500G@0.6ms

- LDPC ECC engine and Block/Page RAID to ensure reliable 3K PE cycles
- Mean Time Between Failure: > 2,000,000 hours
- Data Reliability: Non-recover Read (UBER) ≤10⁻¹⁶
- Serious quality control and assurance

100% NAND Flash screening

High endurance product design with 3D NAND product offerings

Implement high/low temperature dynamic burn-in in each lot production to monitor production quality to meet design specification

Reliability criteria compliant with international standards IEC-60068/61000

